



George W. Tyndall Reliability Technology Samsung Information Systems America San Jose, CA

Introduction

□ Motivation: Designing a reliable HDD requires a rigorous understanding of the most prevalent failure modes/mechanisms, and a means to predict their impact on end-user failure rates.

□ HDD reliability information can be obtained from a variety of sources

End user – Reliability information from customers can be the hardest to obtain, is often times the most ambiguous, and can be difficult to feedback into product design.

<u>Customer qualification</u> – Reliability Demonstration Test (RDT) on well controlled sample distribution to determine intrinsic reliability of product (AFR% / MTBF). Sample size can be limited.

Internal qualification – Highly Accelerated Stress Testing (HAST) during product development to investigate design margins. Drives may not be sufficiently mature, but a substantial number are available.

<u>Subsystem testing</u> – component-level testing (H/M, platform, firmware, channel) to evaluate product feasibility and uncover design limitations

<u>Fundamental studies</u> – Research and development into the scientific underpinnings of current technology, and evaluation of new technologies / alternative designs to meet future product specifications

□ Failure rates from drive-level testing (end-user, customer qualification, and internal qualification) are used to identify the predominant failure mechanisms

Failure of the head-disk interface is found to be the dominant factor impacting HDD reliability

A course-grained model for HDD reliability is developed to address the head-disk interface and the influence of a few vital parameters.

□ Results of drive level testing are presented to vailidate the model

□ Model Refinement – results from component level and fundamental studies

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Failure Modes Summary

□ Highly Accelerated Stress testing results

- Conducted during product development (>10,000 HDD's)
- Dominant failure modes (64%) are HDI related

□ **<u>RDT testing results</u>** (~100 HDD's)

Product	Failure modes	AFR (%)	MTBF (hrs)
80GB/platter (3.5")	1F - PCBA 2F - Disk Scratch 1F - Head Degradation	0.79%	1.11 M
	1F - CND 2F - Disk Scratch 1F - Head Degradation	1.03%	848K
	2F - Disk defects 1F - Weak write 1F - Head Degradation	1.14%	767K

> Majority of failures (75%) are HDI – related

- □ Field Returns Generic failure pareto (1000's HDD)
 - □ Large fraction of "real" HDD failures are HDI-related
- All results point to the head-disk interface as the dominant contributor to HDD reliability

□ Can we develop a deterministic model to predict these failures?







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Failure Analysis – HDI Failures

Dominant HDI-related failure mechanisms and approximate failure rates



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11%

PCBA

CND

Head Degradation

6% 6%

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> 90 – 95% of scratching results from direct contact between flying head and disk

- Majority of head degradation failures result from head-disk contacts
- >100% of all modulation failures result from flying too low "near" contact

□ Majority of HDI-related failures result from the head and disk coming into contact, or near contact

Clearance is key to HDI Reliability



Reduced HDI failure rate requires minimizing head-disk contacts by maximizing clearance

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HDI reliability model

□ Objective: Provide reliability design criteria by modeling clearance, and predicting failure rates, under any given set of operating conditions.

Assumptions

- > Finite clearance \rightarrow 0% failure rate
- > Zero clearance \rightarrow 100% failure rate
- > Not a dynamic model, i.e. no explicit time dependence is incorporated into model

Parameters identified as affecting drive clearance (z) include:

- > Incoming clearance distribution (z_o)
- > Temperature
- > Altitude
- Humidity
- > Duty cycle: Clearance loss during seek (not covered)

□ Sensitivity of clearance on each parameter measured independently

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Clearance is Sensitive to Humidity

Theoretical model developed to describe the effect of humidity on clearance

- Compression under ABS can result in local supersaturation of water vapor
- Supersaturated water vapor is incapable of supporting ABS
- Effective ABS lift drops fly height decreases



Supersaturation





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□ The head-disk clearance decreases with drive humidity



For this HDI design, clearance decreases with water vapor pressure as – 0.2 nm/kPa (comparable to altitude effect)

> For example, clearance at 60 C drops by 3. 5 nm when the humidity is increased from $0 \rightarrow 90\%$ RH

(Strom et al., IEEE Trans. Magn. (2007), <u>43</u>, 3301)

Reliability / failure rate model

Model structure



> The failure predictions were then compared directly with results obtained from standard HDD reliability testing conducted under the specified temperature / altitude / humidity conditions

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Model Verification – Failure rate vs Altitude and Temperature

Conditions: Variable altitude test conducted at two temperatures

Clearance $(nm) = z_0 - a\Delta T - b\Delta P - f(RH)$

Experimental vs Model results





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Quantitative agreement found between model and experiment

- > Failure rate increases with increasing temp
- Failure rate increases with increased altitude

Humidity impact on drive reliability

*****Model failure rate predictions vs Experimental Data

Conditions: Fixed Temperature (T = 70°C) / variable humidity (5 – 95%) Clearance $(nm) = z_0 - a\Delta T - b\Delta P - f(RH)$

Relative Experiment **Predicted Failure Rate** Humidity data 60 0.0% 0.0% 65 6.3% 3.9% 70 12.2% 12.0% 75 25.5% 30.6% 80 66.4% 65.8% 90 99.0% 100.0%



Excellent agreement observed

Indicates validity of approach for clearance / humidity dependence

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Summary of clearance-based reliability model

- □ A clearance-based reliability model was developed and successfully tested.
- The following parameters affecting clearance have been measured and incorporated in the model:
 - Initial clearance distribution
 - Operating temperature
 - Altitude
 - Internal drive humidity (Developed theoretical model of humidity affect on clearance)
- On the basis of the excellent correlation with experiment we conclude that. slider-disk clearance should be treated as a critical parameter by which to design a mechanically reliable magnetic hard disk drive.
- Cautionary note: The impact of humidity and temperature on drive failure rates in the field cannot be attributed exclusively to the clearance effects discussed above.

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Head-disk Spacing Control

"Fly-height On Demand" (FOD) concept

Head-disk spacing is controlled by resistive heating of the pole tip region of the head





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Thermal actuation is only performed during read and write operations

Since head – disk occur only during FOD actuation, the "effective" duty cycle, and AFR are reduced

Clearance measured by magnetic signal change via the Wallace spacing loss equation

FOD allows for a fourfold decrease in the std. deviation of the clearance.

□ Current FOD systems actively compensate for changes in drive temp, altitude, and humidity

□ Future designs promise to supply real time feedback on spacing fluctuations (analogous to position error signal)



Does FH control solve all our problems?

Finer Details – Glide Avalanche

- Physico-chemical properties of disk lubricant
- Long-term effects of temperature
- > Other adverse impacts of high humidity

□ The Future Challenge



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Magnetic Spacing = Distance from top of media to bottom of head sensor

The effect of intermolecular forces when macroscopic objects are separated by nanoscopic distances – van der Waals interaction forces

Molecularly - Thin PFPE Lubricant Films

- Energetics of molecularly thin PFPE films are dependent on the amount of material present
 - Surface-induced confinement results in properties that deviate substantially from bulk material.
 - Anomalous materials properties presence of disjoining pressure unique to molecularly-thin films
 - Tthickness dependent film properties
 - Lubricant displacement by flying head
 - diffusion coefficients (effective viscosity),
 - Adhesive forces
 - Friction forces

Oscillatory polar surface energy of PFPE films indicates layering phenomenon

- Thermodynamic instabilities develop
- Readily apparent in terraced spreading





Film Thickness

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Lubricant Stability – Autophobic dewetting

- **Ο** Oscillatory polar surface energy, χ^p results in a disjoining pressure ($\Pi = d\chi/dh$) that changes sign as a function of film thickness
- \square Thermodynamic stability requires that $\Pi > 0$
- \square When $\Pi < 0$, film is unstable and will spontaneously dewet.



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Impact of dewetting

Lubricant dewetting produces "soft particles" that can interact with the flying slider

Dewetting of Zdol (MW = 1350)

- Homogenous films observed when film thickness, h, < 10 \square
- Lubricant dewetting occurs at h > 10□

□ Clearance measurements

Acoustic emission results





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Lubricant Stability - Dewetting

□ PFPE lubricant layering on surfaces is ubiquitous



Other surfaces





Effect of carbon composition



Fractal dewetting on Si

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Moisture -- related failures modes

- □ High moisture levels inside drive interior can adversely impact reliability
- □ Failure mechanism #1: Corrosion (well-known phenomenon)
- Failure mechanism #2: Clearance loss due to supersaturation under flying head (included in failure model discussed above)
- Failure mechanism #3: Condensation of long-lived water microdroplets on both heads and disks
 - Droplets are abnormally long-lived
 - Droplets reduce clearance / increase head-disk interaction
 - Decreased reliability



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Schematics of Lubricant Bonding

□ PFPE lubricants are available with a variety of backbone structures, molecular weights and functional end-groups.



-OH functionality = Lower affinity for disk



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Di-hydroxyl = Higher affinity for disk

Lubricants with functionalized end-groups will spontaneously bond to the disk.



Extent of lubricant bonding is dictated by the lube, the temperature and RH.



Lubricant bonding

- Exposure to elevated temperature induces a (reversible) bonding of the lubricant to the disk.
- Bonding adversely impacts lubricant mobility and contact forces



□ Adhesion hysteresis increases with bonded fraction

- Force required to separate the head and disk surfaces increases as the lube bonding ratio increases.
- *Severity of contact* (time in contact) increases as bonded fraction increases
- HDI failure rate will scale with the adhesion hysteresis



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Phase transitions in PFPE lubricants

- □ PPFE bonding kinetics are non-classical
 - Time dependent rate coefficients
 - > 1D diffusion limited reaction
 - Functional form of rate coefficients can change as a function of temperature
 - Results indicative of a phase transition

□ Shear modulated AFM measurements confirm a transition from solid-like to liquid-like behavior

□ Transition temperature is dependent on the lubricant molecular weight, PFPE structure and nature of carbon surface





□ Impact of this change in lubricant mobility on HDI reliability has not been addressed

Future (current) Challenge - Intermolecular Forces

□ It is well known that attractive, intermolecular forces are generated when macroscopic bodies are separated by nanoscopic distances (d < 10 - 20nm).

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For van der Waals forces, the attractive force is dependent on three factors:

$$F \propto rac{gA}{d^2}$$

> g = Geometric factor defining the 'effective' interaction area

➤ A = defines interaction strength between materials on the two surfaces

□ We operate the head-disk interface in a regime where these forces are not insignificant, and will only get more prominent in future products



□ The attractive VDW forces that develop at the HDI reduces the magnitude of the disjoining pressure resulting in a vertical expansion of the lubricant film



Slider II FN d d FFPE Carbon Overcoat

At sufficiently close distances, the lube will "jump" from the disk to the head.

This phenomenon will limit the minimum separation distance, and thereby contribute to the glide avalanche.

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Effect of Molecular Weight on Glide Avalanche



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Both techniques show clearance decreases with increasing PFPE molecular weight



Effect of film thickness on Slider disk interactions

Disjoining pressure characterizing film adhesion decreases rapidly with increasing film thickness

> Thicker films should jump to contact sooner than thinner films

>Experimental results confirm this expectation



Physical Separation (nm)

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□ These results also indicate that Intermolecular forces are currently limiting glide avalanche.

Intermolecular Forces: Adhesion

- Previous results suggest that decreased lubricant film thickness would be beneficial from a clearance perspective
- □ The Adhesive Force generated between the disk and slider (stickiness of interface), increases with decreasing film thickness, however



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Increased adhesive (and frictional) force at low film thickness will increase the severity of any head-disk contact

Pre-contact Frictional Forces

□ Pre – contact Frictional forces are generated at low clearances in films of thicknesses used at the HDI

□ Friction starts at nominally 1.5nm prior to establishment of physical contact

□ Friction signal shows displays a maximum value prior to contact

□ Magnitude of friction maximum scales inversely with film thickness

The origin of these phenomenon are not well understood

□ This could also contribute to defining our minimum separation distance.



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Summary

- □ HDD failure rates can be dominated by the HDI
- □ HDI failure rates depend strongly on clearance
 - Mean clearance
 - Std. deviation of clearance
 - Sensitivity to environmental parameters

□ Interface materials (lube + carbon) dictate HDI performance and can impact

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clearance

- > Lube thickness, type and molecular weight
- Carbon type and thickness
- Temperature and humidity
- Physics underlying many of the interface materials properties is still not understood completely
- Intermolecular forces (both adhesive and friction) will fundamentally limit the lowest head-disk clearance that can be obtained (2 – 3nm)